# **IXYS LDA111 Optocoupler Datasheet**

http://www.manuallib.com/ixys/lda111-optocoupler-datasheet.html

Description

LDA111 is a unidirectional-input optocoupler with a Darlington-transistor output. The LDA111 has a minimum current transfer ratio (CTR) of 300% with a maximum value of 30,000%.

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Parameter	Rating	Units
Breakdown Voltage - BV <sub>CEO</sub>	30	V <sub>P</sub>
Current Transfer Ratio - CTR (typical)	8500	%
Saturation Voltage - V <sub>CE(sat)</sub>	1	V
Input Control Current - I <sub>F</sub>	1	mA

## **Features**

- 100mA Continuous Load Rating
- 3750V<sub>rms</sub> Input/Output Isolation
- Unidirectional Input
- Small 6-Pin Package, Thru-Hole or Surface Mount
- Machine Insertable, Wave Solderable
- Surface Mount Tape & Reel Packaging Available

## **Applications**

- Telecom Switching
- Tip/Ring Circuits
- Modem Switching (Laptop, Notebook, Pocket Size)
- Loop Detect
- Ringing Detect
- Current Sensing

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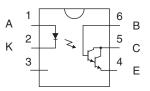
## **Approvals**

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component: TUV Certificate B 09 07 49410 006

## **Ordering Information**

Part Number	Description
LDA111	6-Pin DIP (50/tube)
LDA111S	6-Pin Surface Mount (50/tube)
LDA111STR	6-Pin Surface Mount (1000/Reel)

# **Pin Configuration**





DS-LDA111-R06

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## Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units	
Breakdown Voltage	30	V <sub>P</sub>	
Reverse Input Voltage	5	V	
Input Control Current	100	mA	
Peak (10ms)	1	А	
Power Dissipation			
Input Power Dissipation <sup>1</sup>	150	mW	
Phototransistor <sup>2</sup>	150	TTIVV	
Isolation Voltage, Input to Output	3750	V <sub>rms</sub>	
Operational Temperature	-40 to +85	°C	
Storage Temperature	-40 to +125	۵°	

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

<sup>1</sup> Derate linearly 1.33mW / °C

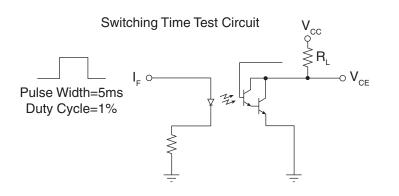
<sup>2</sup> Derate linearly 2mW / °C

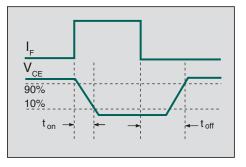
## **Electrical Characteristics @ 25°C**

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics						
Phototransistor Breakdown Voltage	I <sub>C</sub> = 100μA	BV <sub>CEO</sub>	30	85	-	V
Phototransistor Dark Current	$V_{CEO} = 5V, I_F = 0mA$	I <sub>CEO</sub>	-	50	500	nA
Saturation Voltage	I <sub>C</sub> = 3mA, I <sub>F</sub> = 1mA	V <sub>CE(sat)</sub>	-	-	1	V
Current Transfer Ratio	I <sub>F</sub> = 1mA, V <sub>CE</sub> = 2V	CTR	300	8500	30000	%
Output Capacitance	25V, f =1MHz	C <sub>OUT</sub>	-	3	-	pF
Input Characteristics						
Input Control Current	$I_{C} = 3mA, V_{CE} = 2V$	۱ <sub>۶</sub>	-	0.07	1	mA
Input Voltage Drop	I <sub>F</sub> = 5mA	V <sub>F</sub>	0.9	1.2	1.4	V
Reverse Input Current	V <sub>R</sub> = 5V	I <sub>R</sub>	-	-	10	μΑ
Common Characteristics	t	-1				
Capacitance, Input to Output	-	C <sub>I/O</sub>	-	3	-	pF

# Switching Characteristics @ 25°C

Characteristic	Symbol	Test Condition	Тур	Units
Turn-On Time	t <sub>on</sub>	$V_{CC}$ =5V, I <sub>F</sub> =1mA, R <sub>L</sub> =500 $\Omega$	8	
Turn-Off Time	t <sub>off</sub>		345	μs





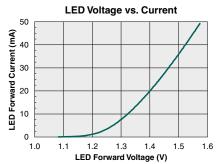
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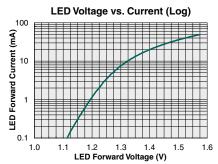
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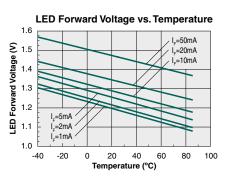


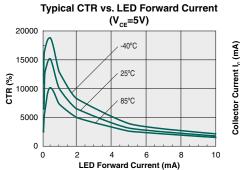
# LDA111

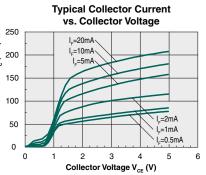
## PERFORMANCE DATA @25°C (Unless Otherwise Noted)\*

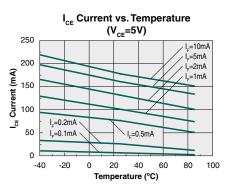


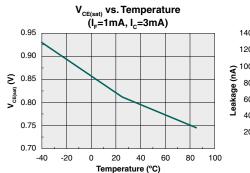


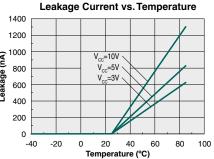


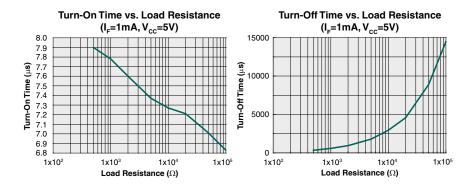












\*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

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#### **Manufacturing Information**

#### **Moisture Sensitivity**

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LDA111/LDA111S	MSL 1

#### **ESD Sensitivity**

This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

#### **Reflow Profile**

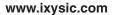
This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
LDA111 / LDA111S	250°C for 30 seconds

#### **Board Wash**

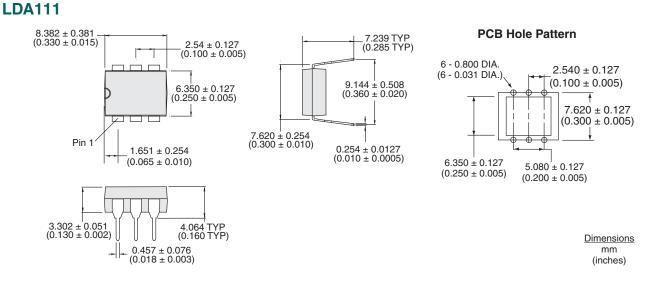
IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



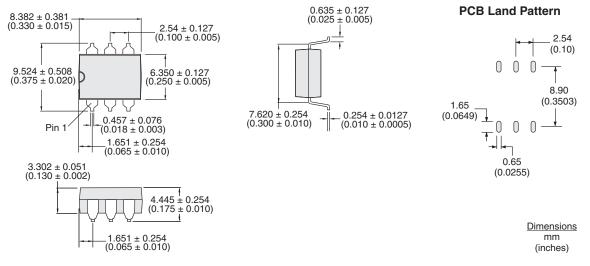




## **Mechanical Dimensions**



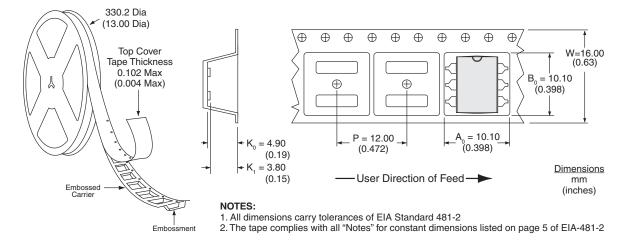
#### **LDA111S**



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#### LDA111STR Tape & Reel



#### For additional information please visit our website at: www.ixysic.com

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